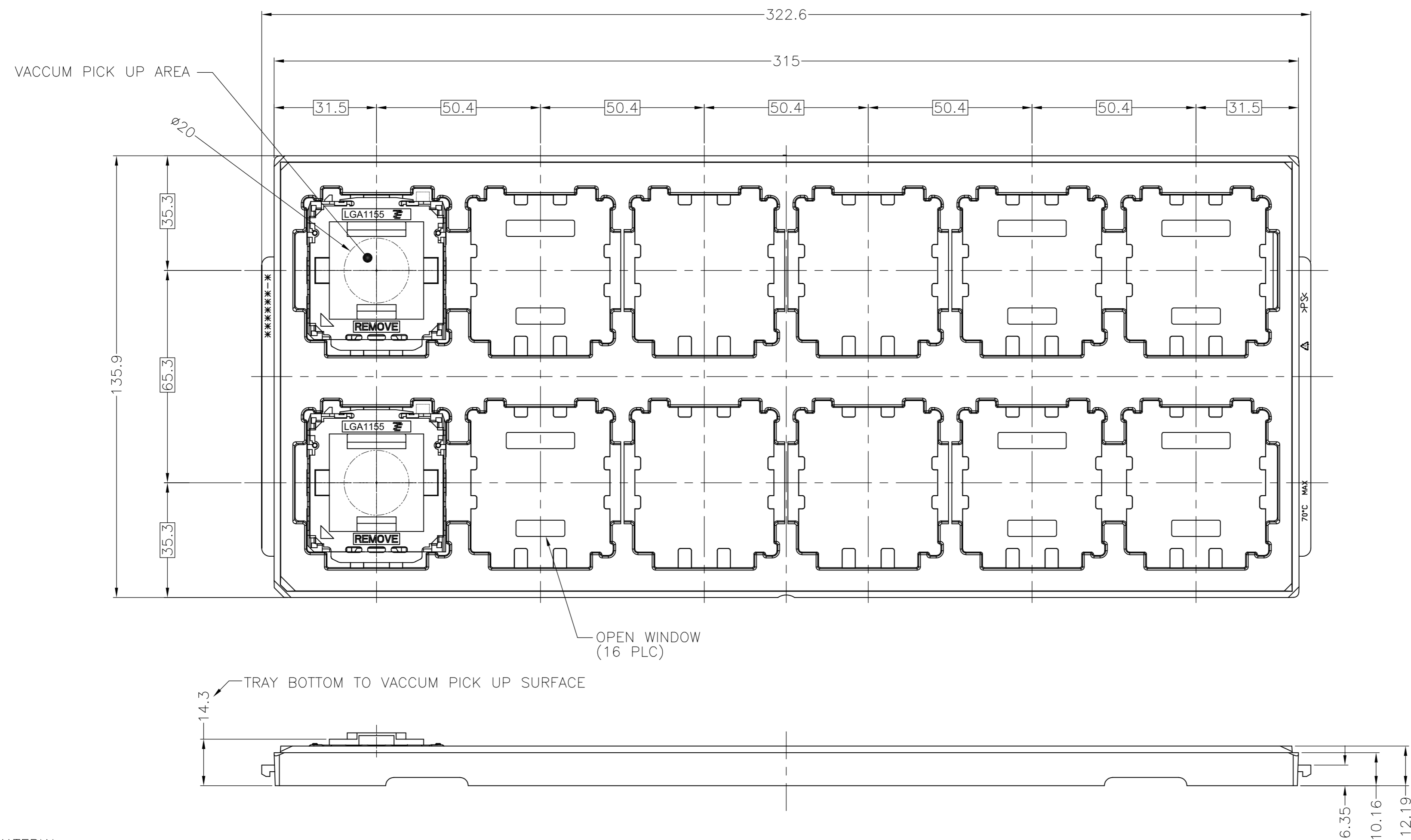


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LOC	DIST	REVISONS		
J	-	P	LTR	DESCRIPTION
		E2	REVISED	DATE DWN APVD
				09JUL'12 H.K T.N



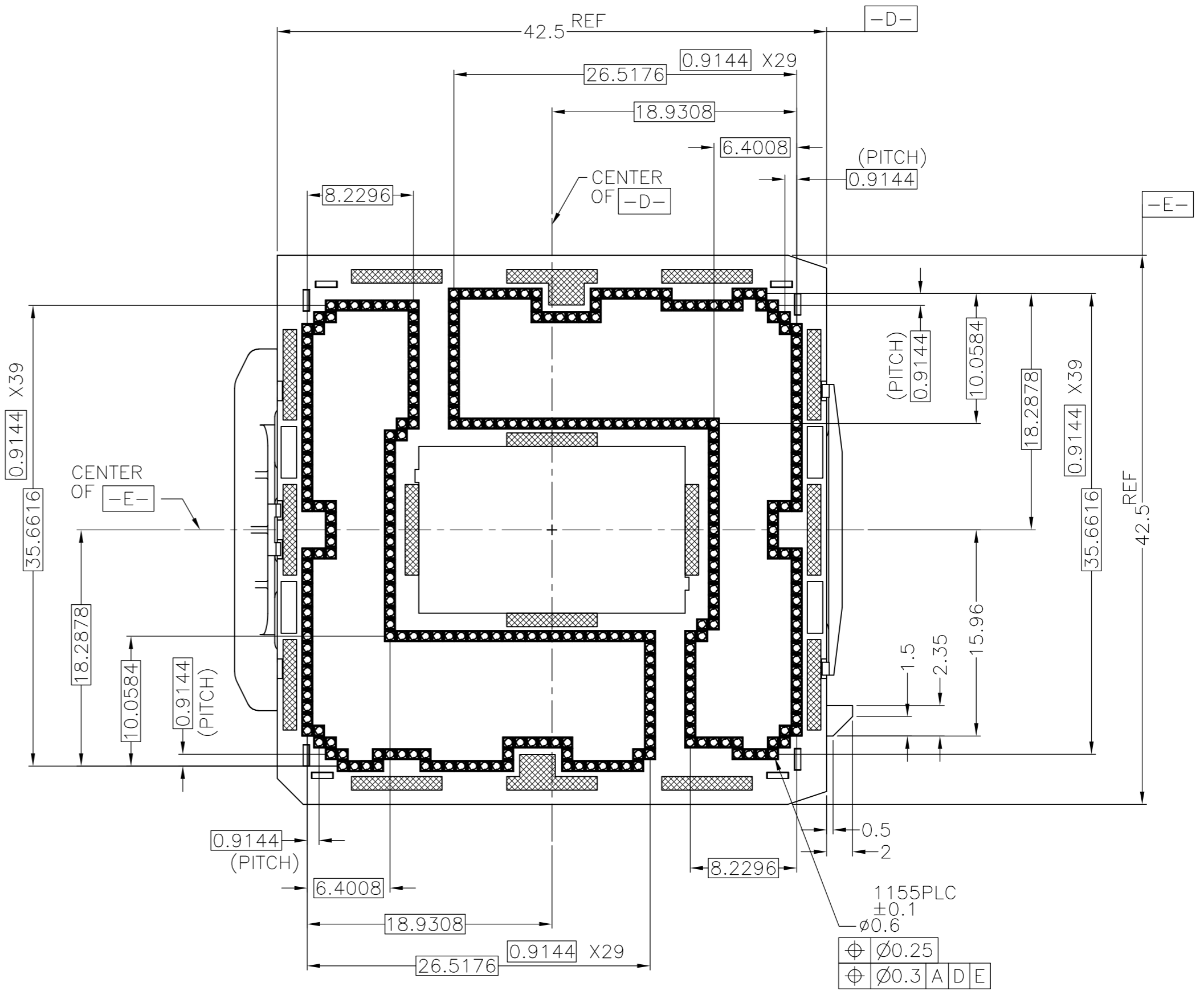
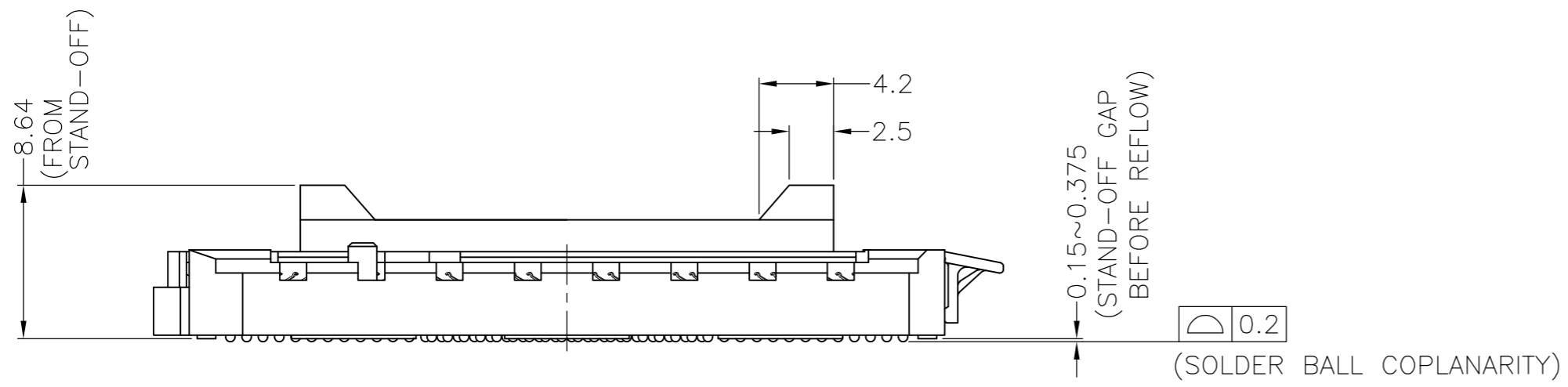
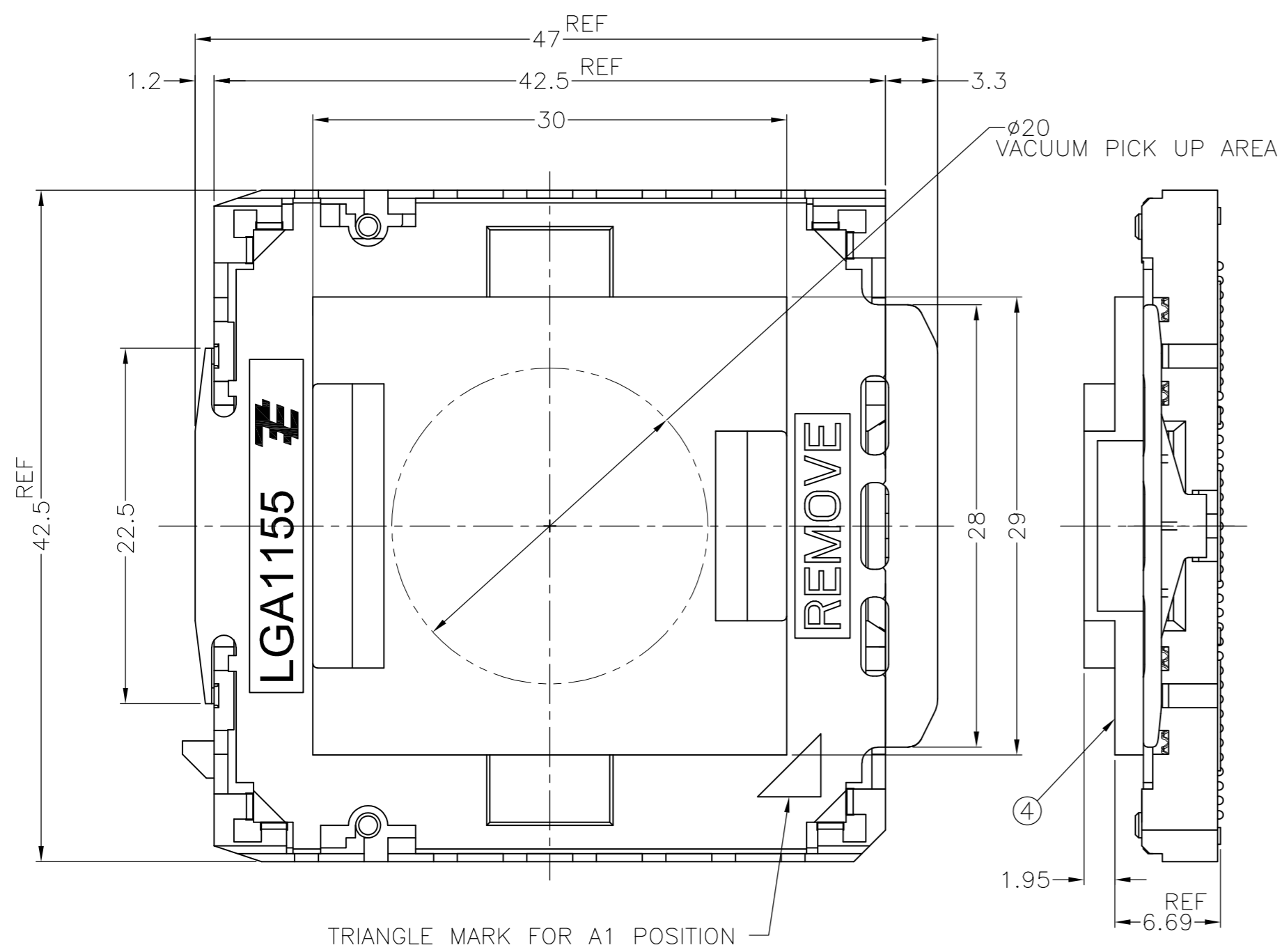
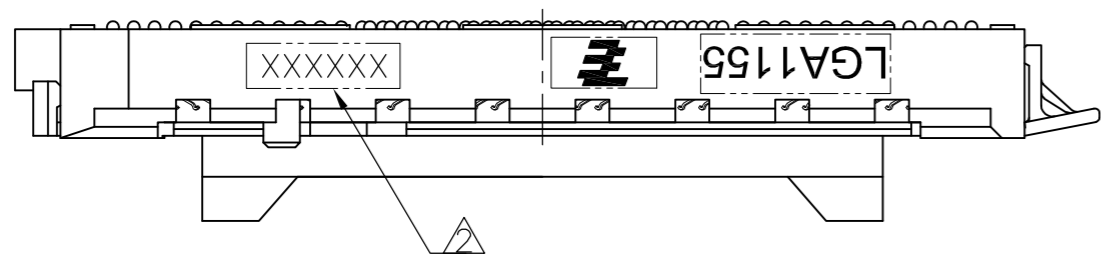
1. MATERIAL
- ① HOUSING : HIGH TEMP, THERMO-PLASTIC, UL94V-0, BLACK
  - ② CONTACT : COPPER ALLOY  
FINISH : Au PL. AT CONTACT AREA ON OVERALL OVER Ni UNDER PL. 0.00127 MIN.
  - ③ SOLDER BALL : Sn/Ag/Cu
  - ④ CAP : HIGH TEMP. THERMO-PLASTIC, UL94V-0, BLACK
- △ INDICATED DATE CODE ON THE HSG

2069965-3	GOLD FLASH PL
2069965-2	0.76 um MIN Au PL
2069965-1	0.38 um MIN Au PL
PART NUMBER	DESCRIPTION

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	J.MIZUSHIMA	10JUN2010	 TE Connectivity	NAME SOCKET ASSY LGA1155
DIMENSIONS: 単位: 純 mm		CHK	H.TAGUCHI	10JUN2010		
TOLERANCES UNLESS OTHERWISE SPECIFIED: 一般公差		APVD	T.NAKASHIMA	10JUN2010		
0-PLC ± ±0.5 1-PLC ± ±0.5 2-PLC ± ±3° 3-PLC ± ± 4-PLC ± ± ANGLES ± ±		PRODUCT SPEC	108-78586			
MATERIAL 材料	FINISH 仕上	APPLICATION SPEC	114-5444		SIZE	A2
		WEIGHT	9.8g		CAGE CODE	00779
		CUSTOMER DRAWING			DRAWING NO	C=2069965
		SCALE	1:1		SHEET	1 of 5
		REV	E2			

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LOC		DIST		REVISIONS			DATE	DWN	APVD
P	LTR	DESCRIPTION							
-	-	SEE SHEET 1			-	-	-	-	-

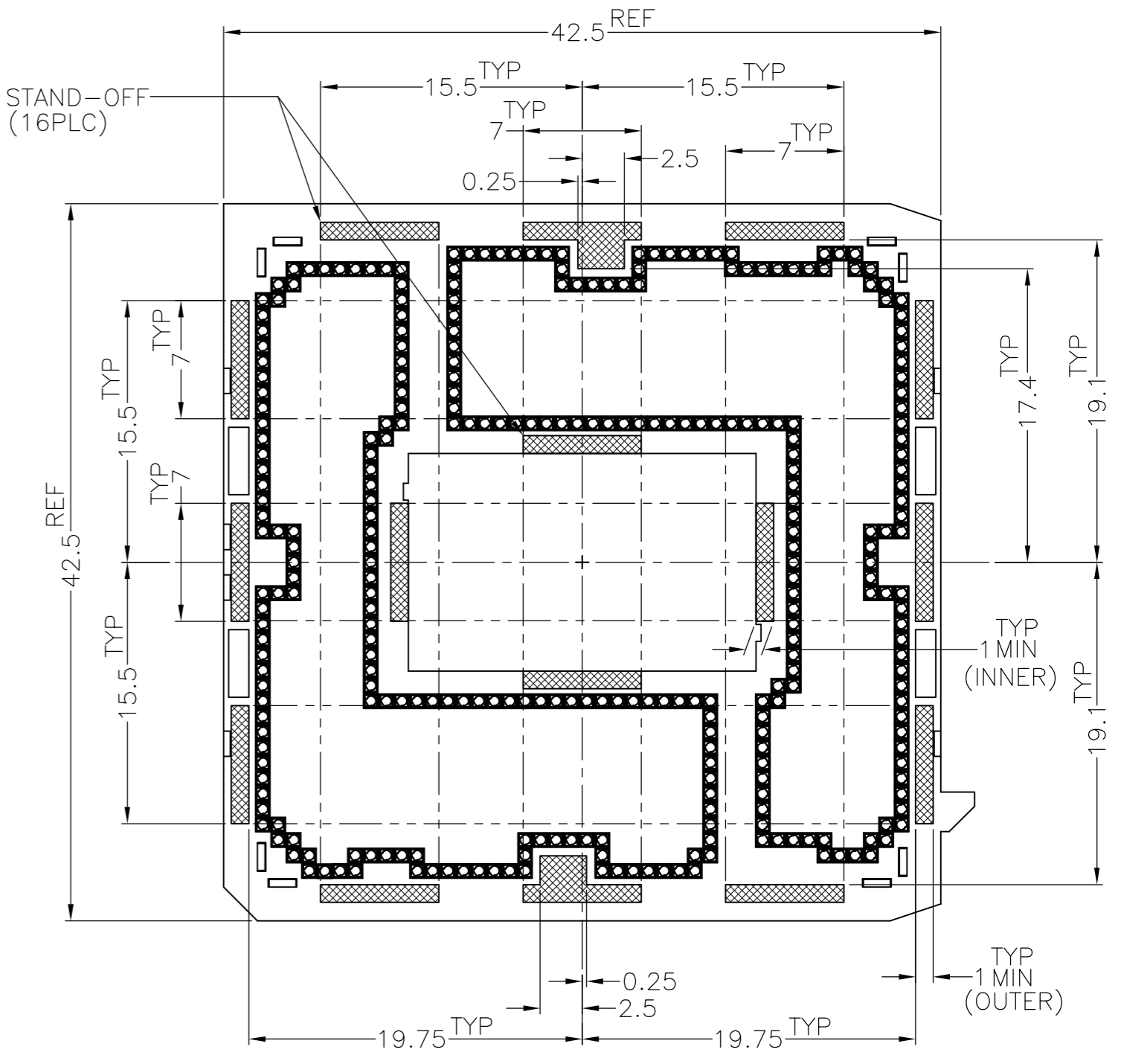
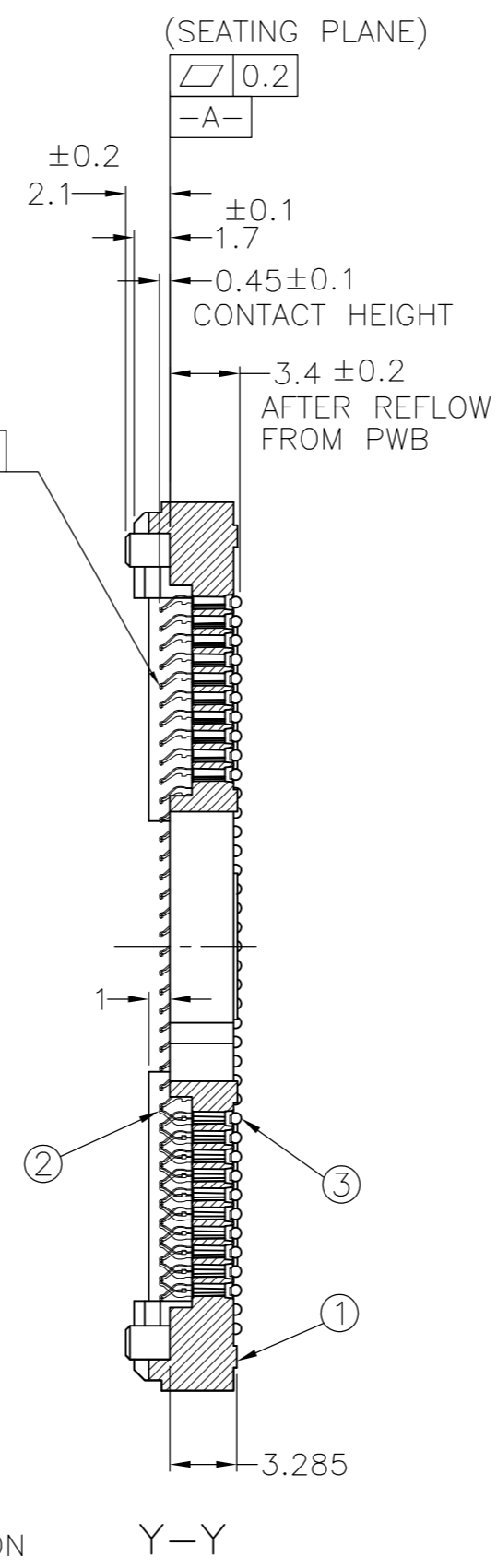
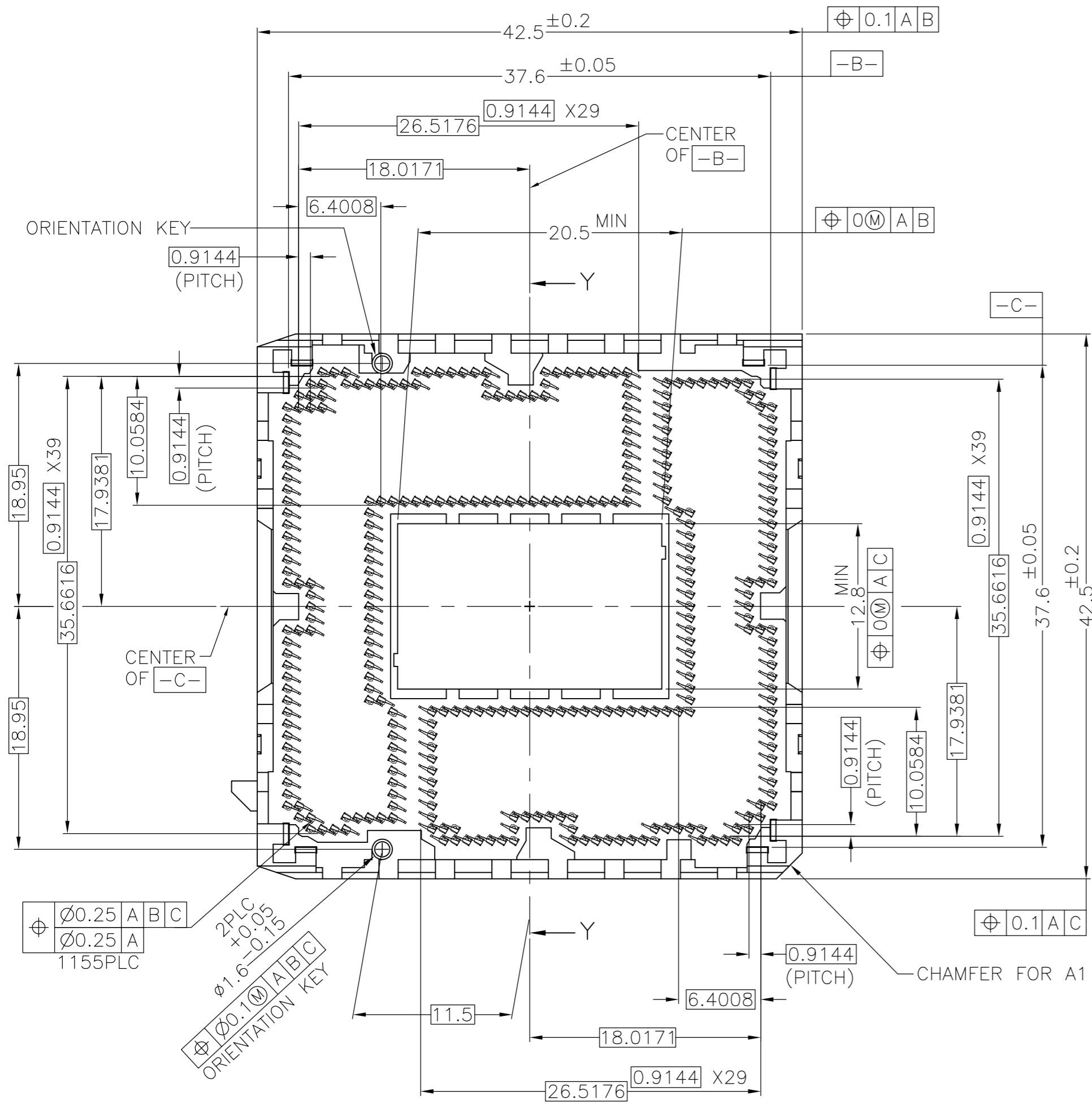


2069965-1, -2, -3 : AS SHOWN

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	-	TE Connectivity		NAME		SOCKET ASSY	
DIMENSIONS: 単位: 寸 mm		CHK	-			LGA1155		SIZE	CAGE CODE
TOLERANCES UNLESS OTHERWISE SPECIFIED: 一般公差		APVD	-	PRODUCT SPEC		A2	00779	C=2069965	-
0 PLG ± ±0.3 1 PLG ± ±0.3 2 PLG ± ±0.3 3 PLG ± ±0.3 4 PLG ± ±0.3 ANGLES ± ±		APPLICATION SPEC	-	取付適用規格		SCALE	NTS	SHEET	2 OF 5
MATERIAL 材料		WEIGHT	-	CUSTOMER DRAWING		REV	E2		

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LOC		DIST		REVISIONS			DATE	DWN	APVD
P	LTR	DESCRIPTION							
-	-	SEE SHEET 1			-	-	-	-	-

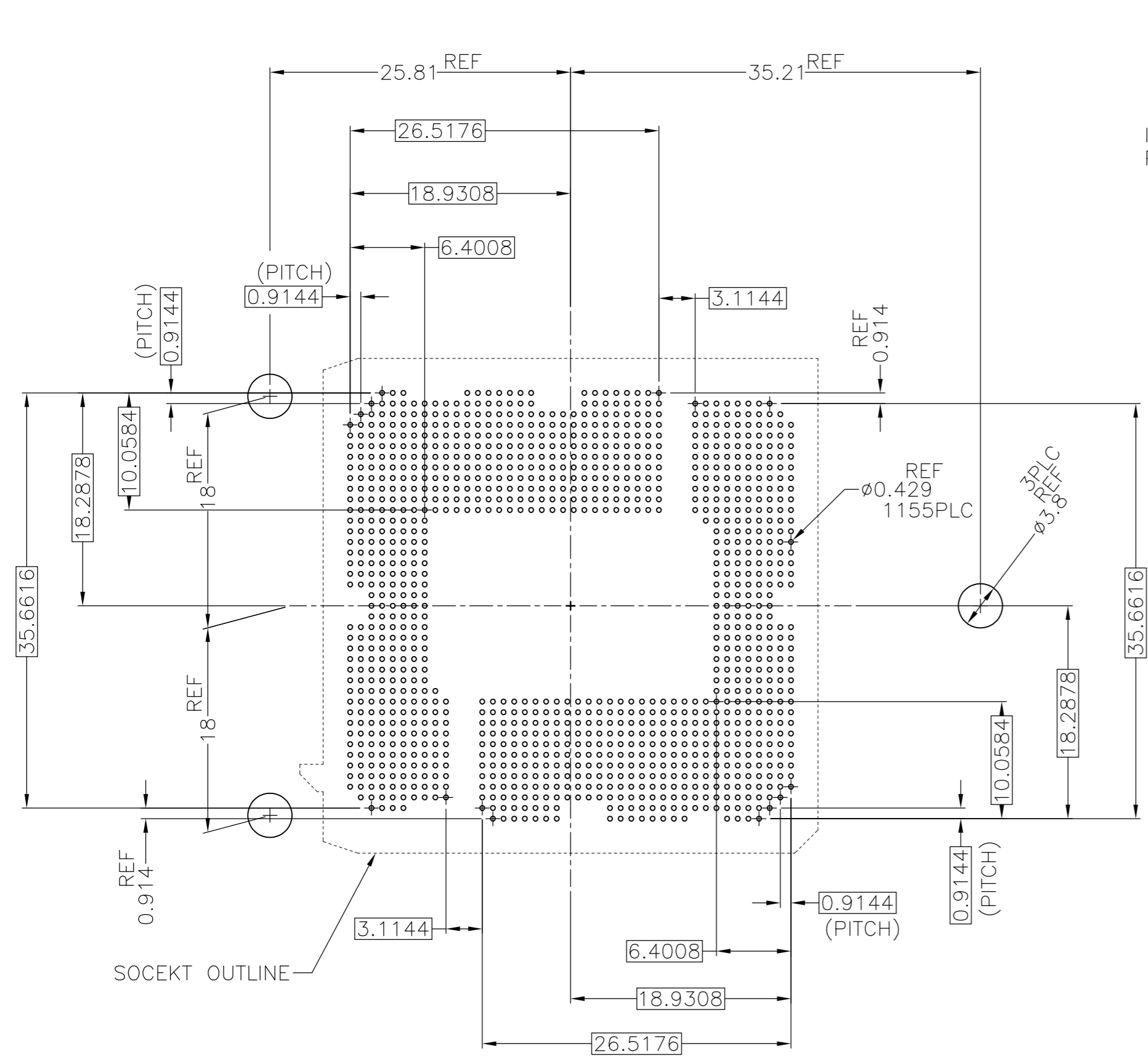


THESE VIEWS DON'T SHOW CAP

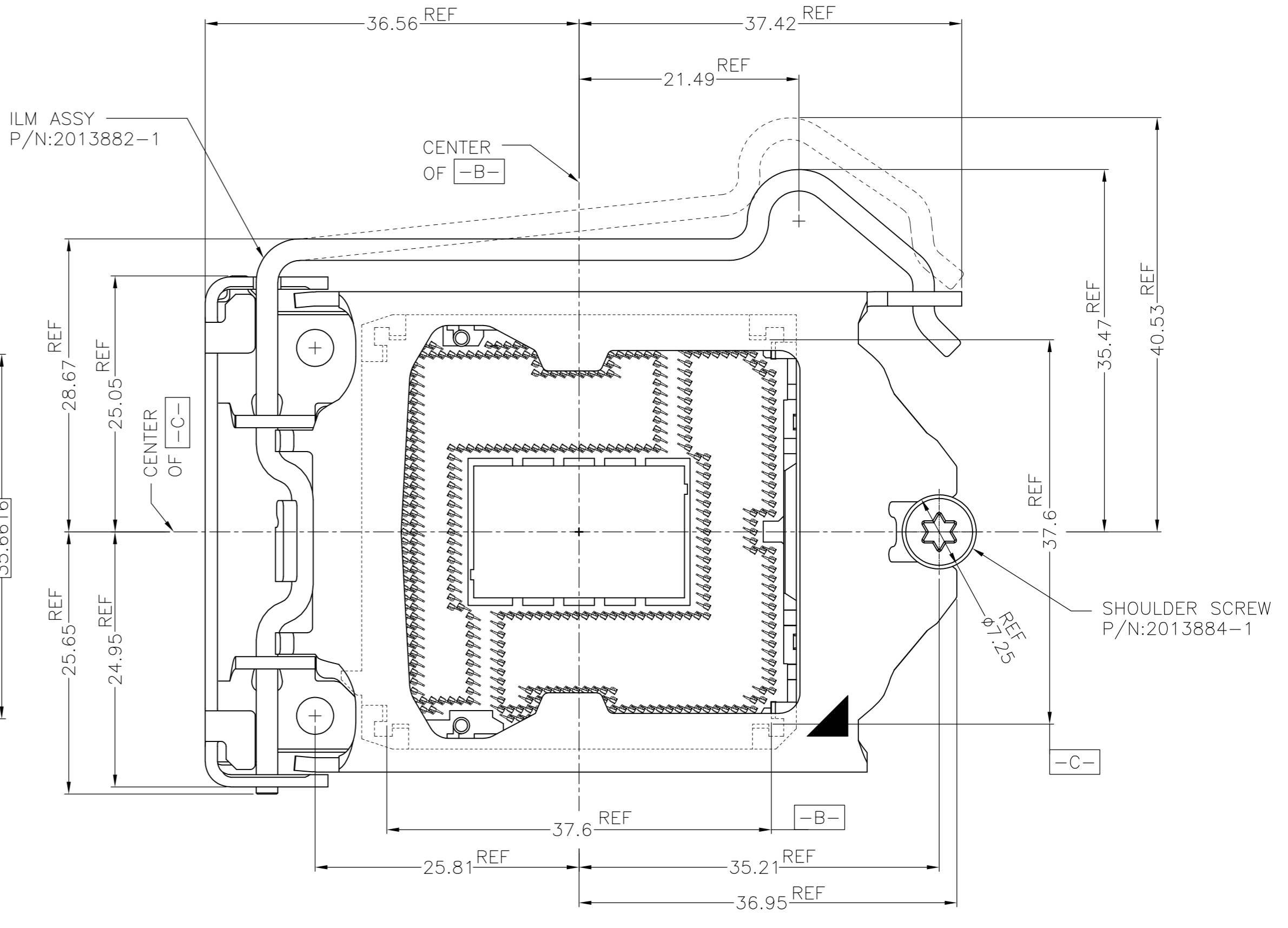
2069965-1, -2, -3 : AS SHOWN

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	-	TE Connectivity SOCKET ASSY LGA1155		NAME	-
DIMENSIONS: 単位: 寸 mm		CHK	-			PRODUCT SPEC	製品規格
TOLERANCES UNLESS OTHERWISE SPECIFIED: 一般公差		APVD	-	APPLICATION SPEC	取付適用規格	CAGE CODE	00779
Ø PLG ± ±0.3 1 PLG ± ±3° 2 PLG ± ±3° 3 PLG ± ± 4 PLG ± ± ANGLES ± ±		WEIGHT	-	DRAWING NO	番号	SCALE	NTS
MATERIAL 材料		FINISH 仕上		C=2069965		SHEET	3 of 5
		CUSTOMER DRAWING		REV		E2	

LOC		DIST		REVISIONS				DATE	DWN	APVD
P	LTR	DESCRIPTION								
-	-	SEE SHEET 1			-	-	-	-	-	



REFERENCE PATTERN LAYOUT



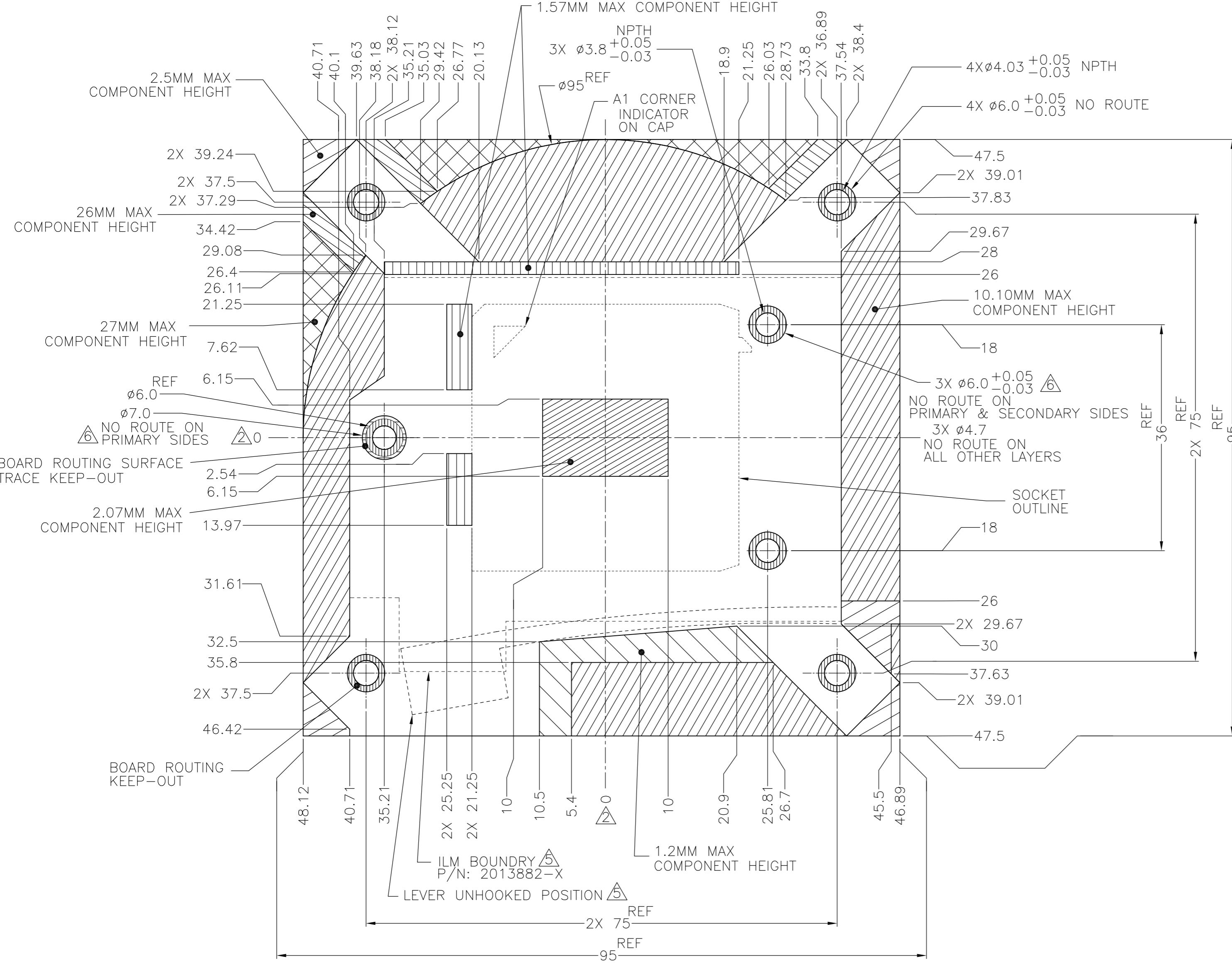
ILM ASSEMBLY OCCUPATION AREA (REFERENCE)  
 CAP IS NOT SHOWN ON THIS VIEW

FOR GENERAL BOARD DESIGN, PLEASE REFER TO THE THERMAL AND MECHANICAL DESIGN GUIDELINES(TMDG) PROVIDED BY INTEL CORPORATION

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	-	TE Connectivity NAME SOCKET ASSY LGA1155	
DIMENSIONS: 单位: 毫米 mm		CHK	-		
TOLERANCES UNLESS OTHERWISE SPECIFIED: 一般公差		APVD	-	SIZE	A2
0 PLG ± 0.3 1 PLG ± 0.3 2 PLG ± 0.3 3 PLG ± 0.3 4 PLG ± 0.3 ANGLES ±		PRODUCT SPEC	-	CAGE CODE	00779
MATERIAL 材料		APPLICATION SPEC	-	DRAWING NO	C=2069965
FINISH 仕上		WEIGHT	-	RESTRICTED TO	-
		CUSTOMER DRAWING	-	SCALE	NTS
				SHEET	4 OF 5
				REV	E2

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LOC	DIST	REVISIONS					
		P	LTR	DESCRIPTION	DATE	DWN	APVD
-	-	-	-	SEE SHEET 1	-	-	-



- NOTES (APPLIED TO SHEET 5 OF 5):
1. DIMENSIONS ARE IN MILLIMETERS
  2.  $\triangle$  GEOMETRIC CENTER OF SOCKET HOUSING CAVITY
  3. BOARD COMPONENT KEEP-INS AND MECHANICAL COMPONENT KEEP-OUTS TO BE UTILIZED WITH SUFFICIENT ALLOWANCES FOR PLACEMENT AND SIZE TOLERANCES, ASSEMBLY PROCESS ACCESS, AND DYNAMIC EXCURSIONS.
  4. ASSUME SYMMETRY FOR UNDIMENSIONED CORNERS AND EDGES.
- $\triangle$  FOR UNDEFINED DIMENSIONS, REFER TO THERMAL AND MECHANICAL DESIGN GUIDELINE PROVIDED BY INTEL CORPORATION.
- $\triangle$  COPPER PAD ON PRIMARY SIDE, NON-GROUNDED. COPPER PAD CAN INSET A MAXIMUM OF 0.127MM FROM THE NO ROUTE EDGE
- $\triangle$  COMBINED COMPONENT AND SOLDER PASTE HEIGHT INCLUDING TOLERANCES AFTER REFLOW.

LEGEND	
	SOCKET/THERMAL/MECHANICAL COMPONENT KEEP-INS
	10.10MM MAX COMPONENT HEIGHT $\triangle$
	1.57MM MAX COMPONENT HEIGHT $\triangle$
	1.2MM MAX COMPONENT HEIGHT $\triangle$
	BOARD ROUTING KEEP-OUT
	27MM MAX COMPONENT HEIGHT $\triangle$
	BOARD ROUTING SURFACE TRACE KEEP-OUT $\triangle$
	2.07MM MAX COMPONENT HEIGHT $\triangle$
	2.5MM MAX COMPONENT HEIGHT $\triangle$
	26MM MAX COMPONENT HEIGHT $\triangle$

COMPONENT KEEP-INS AND MECHANICAL COMPONENT KEEP-OUTS  
 FOR REFERENCE ONLY, PLEASE REFER TO THE THERMAL AND MECHANICAL  
 DESIGN GUIDELINES(TMDG) PROVIDED BY INTEL CORPORATION

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	-	TE Connectivity	
DIMENSIONS: 単位: 寸 mm		CHK	-		
TOLERANCES UNLESS OTHERWISE SPECIFIED: 一般公差		APVD	-	NAME 名称	
$\phi$ PLG $\pm$ 0.3 + PLG $\pm$ 0.3 - PLG $\pm$ 0.3 3 PLG $\pm$ 0.3 4 PLG $\pm$ 0.3 ANGLES $\pm$ 0.3		PRODUCT SPEC	-	SOCKET ASSY LGA1155	
MATERIAL 材料		APPLICATION SPEC	-	SIZE	A2
FINISH 仕上		WEIGHT	-	CAGE CODE	00779
		CUSTOMER DRAWING	-	DRAWING NO	C=2069965
				RESTRICTED TO	-
				SCALE	NTS
				SHEET	5 OF 5
				REV	E2